

Silicone Thermal Pad / XK-P30

Introduction

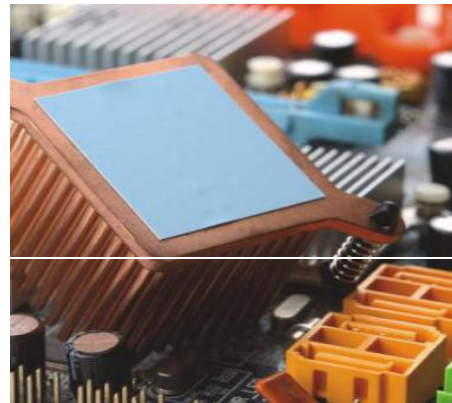
This series of products are resilient and with large deformation, suitable for large institutional design tolerances. Single or double layer structure, The Double layer is reinforced with special ultra-thin fabric to increase resistance and workability of puncture, strip type, malformation designs. Self-adhesive and never recede. No corrosion to the Copper surface, "environmentally friendly products".

Features

Ultra conformable, "gel-like" modulus
Designed for low-stress applications
low hardness

Applications

Telecommunications
Computer, Between heat-generating semiconductor and a heat sink



	unit	XK-P30	Method
Reinforcement Carrier		-	
Inherent Surface Tack (1-/2- sided)		2-side	
Color		Light Blue	visual
Thickness	mm	0.3~5.0	ASTM D374
Specific Gravity	g/cm ³	3.1	ASTM D792
Hardness	Asker C	15~20	JIS K7312
	Shore 00	40~50	ASTM D2240
Thermal impedance@0.5mm 14.5psi	°Cin ² /W	0.28	ASTM D5470
Thermal Conductivity	W/mK	3.0	HOT DISK
Volume Resistivity	Ωcm	>10 ¹³	ASTM D257
Breakdown Voltage	KV/mm	>10	ASTM D149
Dielectric Constant	1	7	ASTM D150
Application temperature	°C	-50~200	
Tensile strength	psi	13	ASTM D149
Elongation	%	80	ASTM D149
Siloxane Volatiles D4~D20	%	<0.01	GC-FID
Flammability	UL94	V-0	UL94